

2019 ICEET

Tuesday, June 4, 2019

TIME	
7:00am	REGISTRATION OPENS
	Professional Development Courses
8:30am-12:00pm	AM COURSE: Failure Analysis of Electronic Devices Martine Simard-Normandin, Ph.D., MuAnalysis, Inc.
12:00pm-1:30pm	LUNCH BREAK
1:30pm-5:00pm	PM COURSE: Tolerance Mistaken: Impacts of Not Properly Addressing Limitations of Material, Industry Standards and Assembly Process Limitations Dale Lee, Plexus Corp.

Wednesday, June 5, 2019

TIME	
7:00am	REGISTRATION OPENS
	Session 1: Solder Materials Chair: Jason Keeping, P.Eng., Celestica, Inc. Co-Chair: Jason Rogers, M.G. Chemicals
8:00am-8:30am	Evaluation of Tin Whisker Formation of Discrete Capacitor Components Assembled with Bismuth-Containing Lead-Free Solder Alloys after Long-Term Ambient Temperature, High Humidity Storage Andre Delhaise, Ph.D., Celestica, Inc.
8:30am-9:00am	The Effect of Temperature and Atmosphere on the Sublimation of Some Dicarboxylic Acids Used in Fluxes Bev Christian, Ph.D., Independent Consultant
9:00am-9:30am	Microstructural Evolution of Solder Joint under High Temperature Service Jie Geng, Ph.D., Indium Corporation
9:30am-10:00am	A Case Study of Lead-free Solder Process Cross-Contamination Dave Hillman, Collins Aerospace
10:00am-10:30am	REFRESHMENT BREAK
	Session 2: Solder Materials Part 2 Chair: Martine Simard-Normandin, Ph.D., MuAnalysis Inc. Co-Chair: Sutharshan Suppiramaniam, Johnson Controls
10:30am-11:00am	High Reliability Lead-Free Solder Alloys for High Brightness LED Application Jie Geng, Ph.D., Indium Corporation
11:00am-11:30am	Low Temperature Transient Liquid Phase Bonding for Joining SIC Power Modules Jae Pil Jung, University of Seoul, South Korea
11:30am-12:00pm	Flux Medium and Voiding: an Empirical Study Sirine Bayram, Ph.D., AIM Solder
12:00pm-1:00pm	LUNCH BREAK
	Session 3: Keynote Chair: Bev Christian, Ph.D., Independent Consultant Co-Chair: Carlo Busquit, GVA Lighting Inc.
1:00pm-1:45pm	KEYNOTE: Dealing with the Challenges in the New Advanced Packaging Era E. Jan Vardaman, TechSearch International, Inc.
1:45pm-2:15pm	Smart Textile Applications in Medical Devices & Senior Care Alex Chen, P.E., Celestica, Inc. ; Milad Afshar, Ph.D., Myant Inc.
	Short Supplier Presentations, Posters, Refreshments
2:30pm-2:40pm	Indium Corporation
2:40pm-2:50pm	Seika Machinery, Inc.
2:50pm-3:00pm	StaticStop, Inc.
	Session 4: Industry Wide Chair: Peter Arrowsmith, Ph. D., Ops A La Carte Co-Chair: Bev Christian, Ph.D., Independent Consultant
3:00pm-3:30pm	Industry 4.0 the Next Industrial Revolution - The Smart Factory MB Allen, KIC
3:30pm-4:00pm	Update to: Aftermarket LED-Based Electronic Devices, Buyer Beware Martine Simard-Normandin, Ph.D., MuAnalysis Inc.
4:00pm-4:30pm	How to Integrate IP with your Electronic Technology Tony Orsi, Bereskin & Parr
5:00pm	FACILITY TOUR: Microart Services Inc. (EMS facility in Markham)

Thursday, June 6, 2019

TIME	
7:00am	REGISTRATION OPENS
	Session 5: Harsh Environment & Fiber Optics Chair: Dave Hillman, Collins Aerospace Co-Chair: Jason Keeping, P.Eng., Celestica, Inc.
8:00am-8:30am	Electrical Test Method Advances on Specific Components and Their Response to the Environment Mike Bixenman, DBA, MBA, KYZEN Corporation
8:30am-9:00am	Protecting Flat Conductor Cables in Aggressive Space Environments Jacob Kleiman, Integrity Testing Laboratory Inc.
9:00am-9:30am	Optical Sensors: A Fundamental Shift in Collecting Data in Harsh Environments Nicholas Burgwin, P.Eng., Fibos
9:30am-10:00am	Industrial IoT Solutions with Fiber Optic Sensors Hamid Alemohammad, Ph.D., AOMS Technologies
10:00am-10:30am	REFRESHMENT BREAK
	Session 6: Failure Analysis & Reliability Chair: Dale Lee, Plexus Corp. Co-Chair: Bev Christian, Ph.D., Independent Consultant
10:30am-11:00am	Failure Analysis of SAC305 Assemblies for Digital Hearing Aids Mircea Capanu, Ph.D., P.Eng., ON Semiconductor
11:00am-11:30am	Purple Plague Makes a Come Back Martine Simard-Normandin, Ph.D., MuAnalysis, Inc.
11:30am-12:00pm	Power Supply Reliability, Comparison of Field and Test Data Peter Arrowsmith, Ph.D., Ops a La Carte LLC
12:00pm-1:00pm	LUNCH BREAK
	Session 7: Components & Substrates Chair: Andre Delhaise, Ph.D., Celestica, Inc. Co-Chair: Jason Keeping, P.Eng., Celestica, Inc.
1:00pm-1:30pm	Bare Board Insepection by X-ray - Ensuring a Sound Foundation for Assembly David Bernard, Ph.D., David Bernard Consultancy
1:30pm-2:00pm	To Bake or Not to Bake? Large Metallic BGAs in Sealed ESD Bags with no Indication of Humidity Exposure Bihari Patel, Microart Services Inc.
2:00pm-2:30pm	Reliability and Voids in QFN Solder Joints: What's the Issue? Dave Hillman, Collins Aerospace
2:30pm-3:00pm	Influence of PCB Dielectric Material on the Resistance to Trace Cracking During Drop Impact Bev Christian, Ph.D., Independent Consultant
3:00pm-3:30pm	REFRESHMENT BREAK
	Session 8: Ruggedization & Conformal Coating Chair: Peter Arrowsmith, Ph. D., Ops A La Carte Co-Chair: Jason Rogers, M.G. Chemicals
3:30pm-4:00pm	High Performance Light and Moisture Dual Curable Automotive Conformal Coating Aysegul Kascatan Nebioglu, Ph.D., Dymax
4:00pm-5:00pm	Panel Session: Ruggedization - The Next Technology Wave Moderator: Jason Keeping, P.Eng., Celestica Inc. Luka Sovulj, M.G. Chemicals; Weixing Hou, 3M; Carl Thompson, OES
5:00pm	CONFERENCE CONCLUDES